

# Product End-of-Life Disassembly Instructions

**Product Name / Model:** Rugged Tablet / DT302RP

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of DT Research products to remove components and materials requiring selective treatment, as defined by EU Directive 2012/19/EU of the European Parliament and of the Council of 4 July 2012 on waste electrical and electronic equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards Assemblies (PCBA)	With a surface greater than 10 sq cm	1
Mass storage device	Permanently soldered to PCBA	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches,	0
LCD Display	a surface greater than 100 sq cm includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and	Include the cartridges, print heads, tubes, vent chambers, and service	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 SCREW DRIVER(Plum flower head)	
Description #2 HAIR DRYER	
Description #3 KNIFE BLADE	

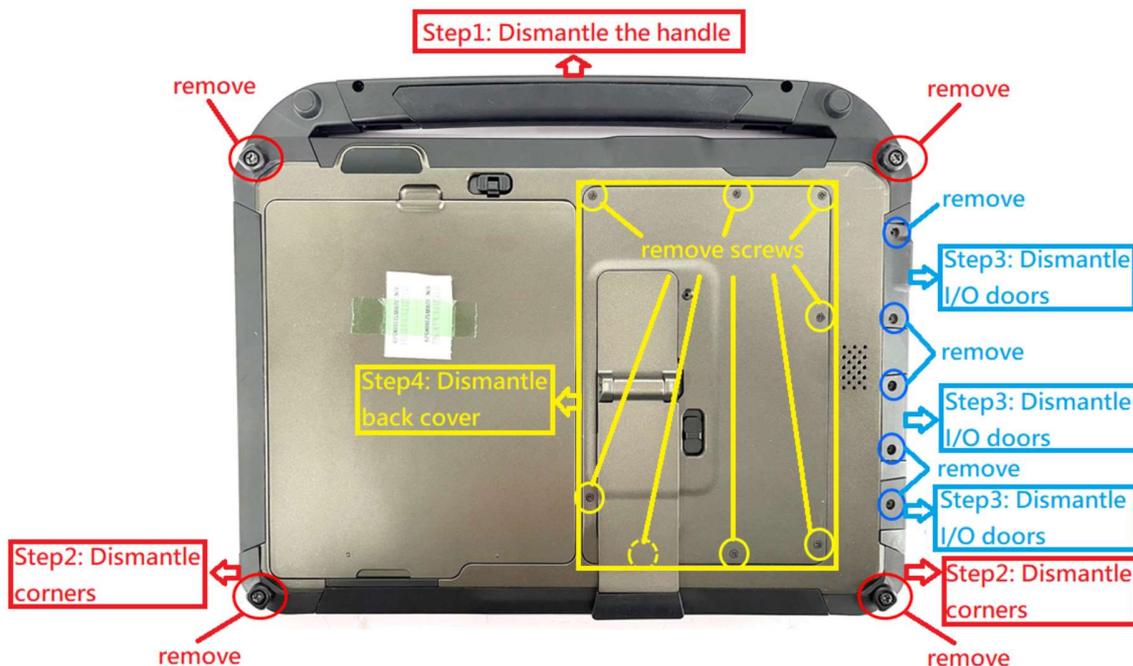
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Dismantle the handle, corners, I/O doors and back cover.
2. Dismantle buttons cover and side frame
3. Dismantle bottom cover, top cover and buckles
4. Remove battery pack
5. Dismantle back-up battery
6. Dismantle rear enclosure
7. Dismantle mother board
8. Dismantle I/O board
9. Dismantle the LCD display

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

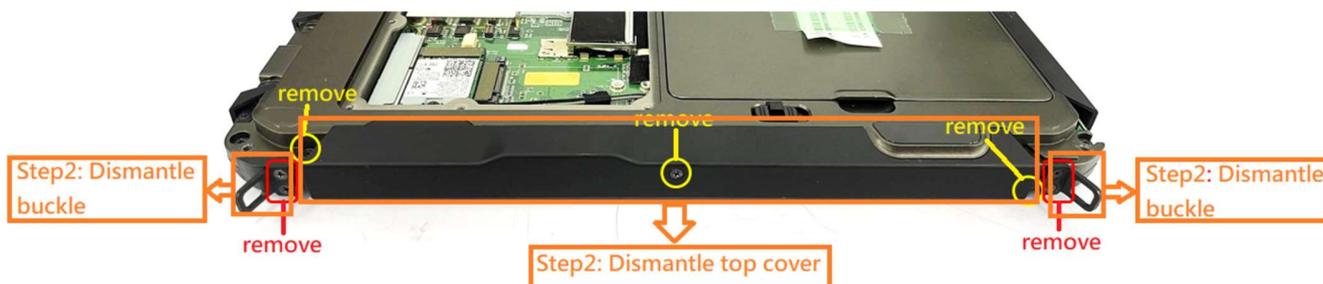
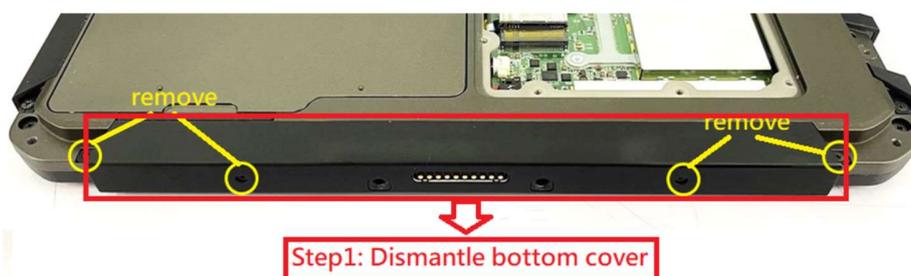
- (1) Dismantle the handle, corners, I/O doors and back cover
- Step 1: remove screws and dismantle the handle (red color line)
- Step 2: remove screws and dismantle corners (red color line)
- Step 3: remove screws and dismantle I/O doors (blue color line)
- Step 4: remove screws and dismantle back cover (yellow color line)



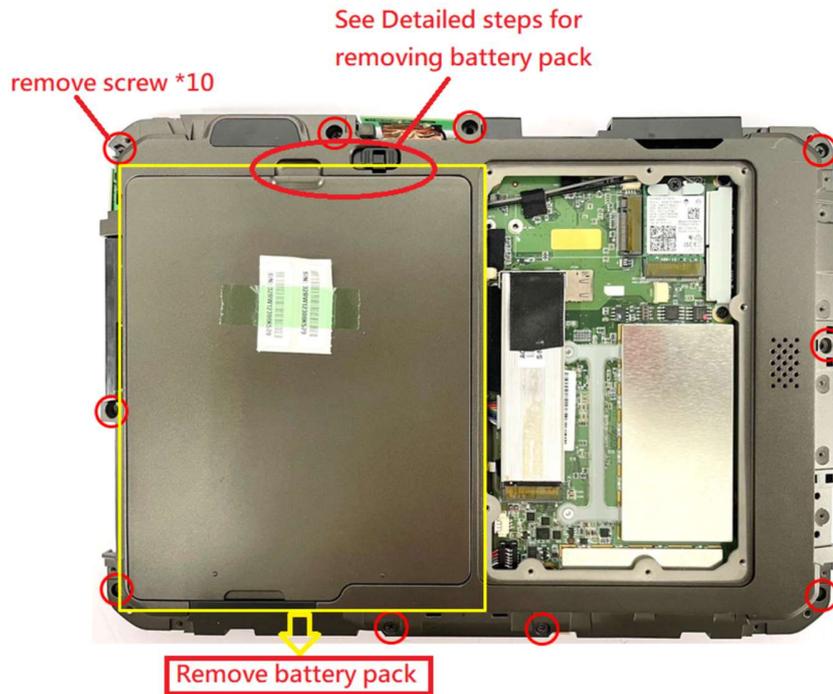
- (2) Dismantle buttons cover and side frame  
Step 1: remove screws and dismantle buttons cover  
Step 2: remove screws and dismantle side frame



- (3) Dismantle bottom cover, top cover and buckles  
Step 1: Dismantle bottom cover  
Step 2: Dismantle top cover and buckles

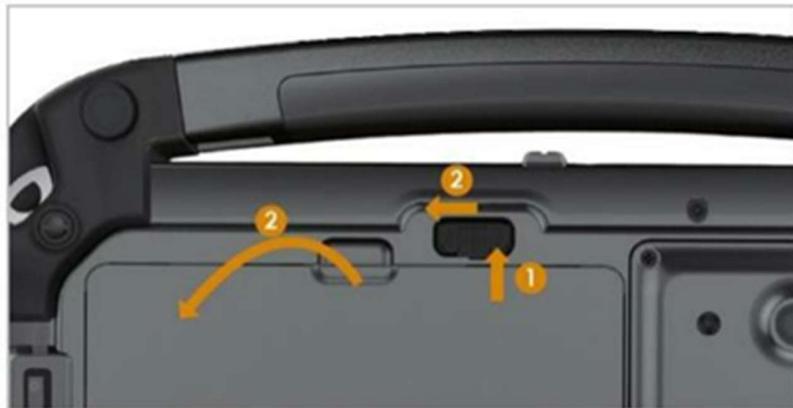


(4) Remove battery pack



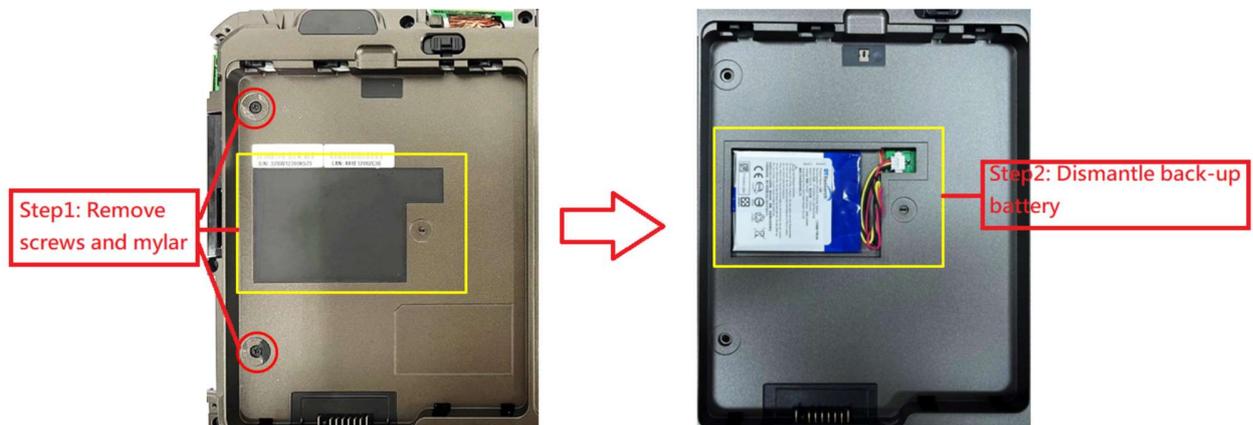
\*\* Detailed steps for removing battery pack

- (1) Slide the battery latch to the unlocked position.
- (2) Lift the battery pack off the compartment.



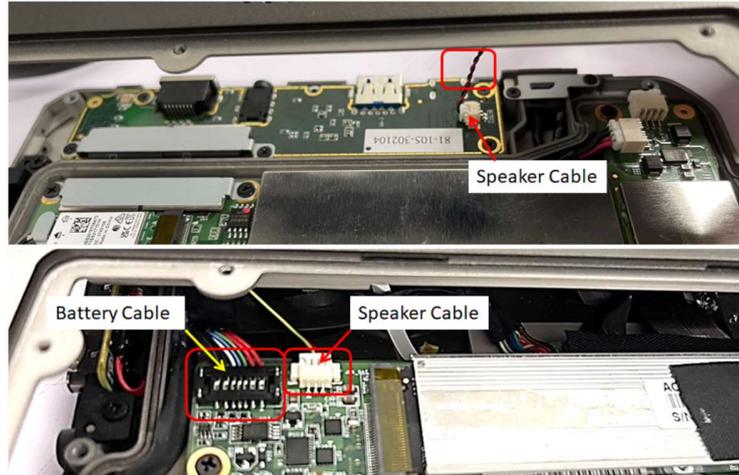
(5) Dismantle back-up battery

- Step 1: Remove screws and mylar
- Step 2: Dismantle back-up battery



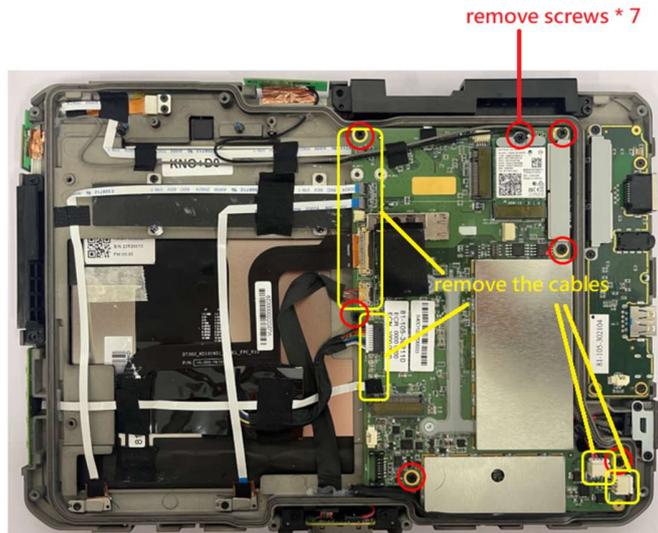
(6) Dismantle rear enclosure

\*\*Remove the cables before the rear enclosure is dismantled.

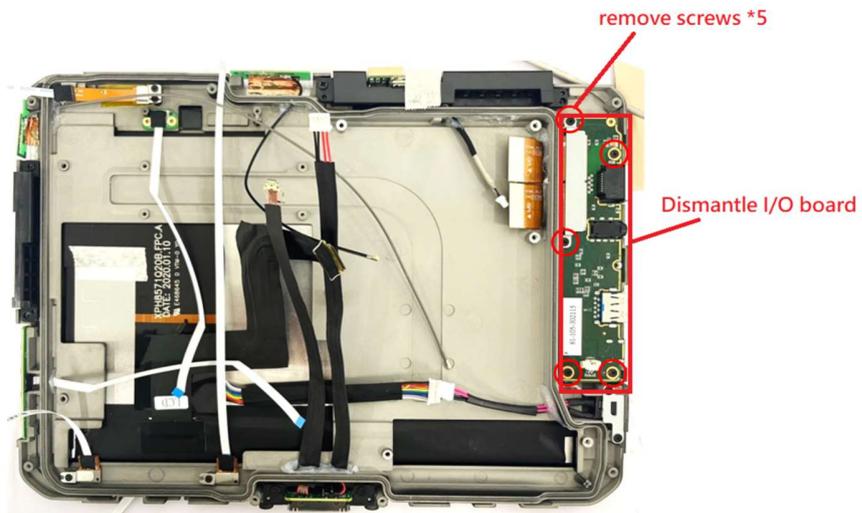


(7) Dismantle mother board

\*\*Remove the screws and cables before the mother board is dismantled.



(8) Dismantle I/O board



(9) Dismantle the LCD display

\*\* Steps:

- (i) Use hair dryer to soften the glue between LCD display and front frame.
- (ii) Use knife blade to cut the glue and lift the LCD display off front frame slowly.

Dismantle LCD Display

